Substitute fo	or form 1449A/PTO	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		Complete if Known
		MAD 2 1 mg	Application Number	10/058,650
INFORM	IATION DISCLOS IENT BY APPLICA	URE^{nan} (2002)	Filing Date	01/28/02
STATEM	IENT BY APPLICA		First Named Inventor	Chemet al.
		112.	Group Art Unit	3723 C
(use as many	sheets as necessary)	RADDIARY	Examiner Name	Unknown 79 63
Sheet	1	of 2	Attorney Docket Number	AP01985(2)

				U. S. PATENT DOCUMENT	rs	B B O
Examiner Initials*	Cite No. ¹	U.S. Patent Number	Kind Code ² (if known)	Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Paĝes, Columns, Lines, Where Relevant Passages or Relevant L'Figures Appear
PN		3,761,784		Jund	07/04/1989	છ
1		4,191,057		Busta	05/27/1997	
\top		4,275,406		Muller et al.	06/23/81	
		4,317,126		Gragg, Jr.	02/23/82	······································
		4,395,451		Althouse	07/26/83	
		4,444,054		Schaff, Jr	04/24/84	
		4,667,944		Althouse	05/26/87	
		4,683,755		Samek	08/04/87	
		4,711,014		Althouse	12/08/87	
		4,986,861		Nishida et al.	01/22/91	
		4,996,627		Zias et al.	02/26/91	
		5,356,176		Wells	10/18/94	
		5,629,486		Viduya et al.	05/13/97	
		5,644,102		Rostoker	07/01/97	
oa		5,917,264		Maruno et al.	06/29/99	
					 	

				FOREIGN	PATENT DOCUME	NTS	•	
Examiner	Cite No. 1	Foreign Patent Document			Name of Patentee or	Date of	Pages, Columns, Lines,	T ⁶
Initials*		Office ³	Number ⁴	Kind Code ² (if known)	Applicant of Cited Document	Publication of Cited Document MM-DD-YYYY	Where Relevant Passages or Relevant Figures Appear	
			_					ــــــ
								
		1						—
_								—
		 	<u> </u>					↓
	ļ							ļ
		<u> </u>						
								<u> </u>
	<u> </u>						L	<u> </u>
		1					1	

F		D.i.		
Examiner	\odot \mathcal{V}	Date	2/11/04	
Signature	Gozbanny	Considered	3/11/04	

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation, if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Unique citation designation number. ² See Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3), ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English Language Translation is attached.

Sheet

	1018E	•
Please type a plus sign (+) inside this bo	□+MAR 2 1 2002	1
Substitute for form 1449A/PTO	AADEMARK ORLY	7
INFORMATION DISCLO STATEMENT BY APPLIC	SURE	

of

2

(use as many sheets as necessary)

2

	Complete if Known	Richard .
Application Number	10/058,650	
Filing Date	01/28/02	100
First Named Inventor	Chen et al.	WAR 2 6 200
Group Art Unit	3723	2002
Examiner Name	Unknown /4	-CHAIOL OF
Attorney Docket Number	AP01985	CHMOLOGY CANTEL BUZZO
		- OF TO

Examiner	Cite	OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book,	Τ
Initials*	No. 1	magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	
DW		"Micromachines on the March" Janusz Bryzek, Kurt Petersen, and Wendell McCulley. IEEE Spectur, May 1994, pp 20-31.	
		"Ultra Thin ICs Open New Dimensions for Microelectric Systems" G. Klink, C. Landesberger, M. Feil, F. Ansorge, R. Aschenbrenner. Advancing Microelectronics, July/August 2000; pp.23-25.	
		"New Process Scheme for Wafer Thinning and Stress-free Seperation of Ultra Thin ICs" C. Landesberger, S. Scherbaum, G. Schwinn, H. Spohrle. Proceedings of Microsystems Technologies 2001; pp. 1-7.	
		"Innovative Packaging Concepts for Ultra Thin Integrated Circuits" G. Klink, M. Feil, F. Ansorge, R. Aschenbrenner, H. Reichl. Electonic Components and Technology Conference, 2001; pp. 1034-1039.	
	-	"Thin Silicon Chips and ACF Connection Technology for Contactless IC Cards" Mitsuo Usami. 1999 International Symposium on Microelectronics; pp. 309-312.	
		"Mechanical Lapping, Handling and Transfer of Ultra-Thin Wafers" S. Pinel, J. Tasselli, J.P. Bailbe, A. Marty, P. Puech and D. Esteve. Microengineering Vol. 8, 1998; pp 338-342.	
	·	"SmartCard Assembly Requires Advanced pre-Assembly Methods" Dr. J. Muller, P. Stampka, W. Kruninger, E. Gaulhofer, H. Oyrer. Semiconductor Internationall, July 2000; pp. 191-200.	
		"Thin Monocrystalline Silicon Films on Flexible Substrates Enable Multiple Transfer Processes" C. berge, Dr. R. Bergmann, D. J. Werner. MRS Bulletin, August 2001; pp. 603.	
	,	Khazan, A.D., "Transductors and Their Elements: Design and Application." Prentice-Hall, Inc. 1994, ISBN 03-13-929480-5. pp 393-395.	-
OV		"Packaging Very High Pressure Transducers for Common Rail Diesel Injection Systems" K. Sidhu, Measurement Specialties, Inc. October 1987, pp. 1-4	

Examiner		Date	2/11/11
Signature	Dorstansmin	Considered	3/11/04

EXAMINER: Initial if reference considered whether or not citation is in conformance with MPEP 609. Draw line through citation, if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Unique citation designation number. ² Applicant is to place a check mark here if English Language Translation is attached.